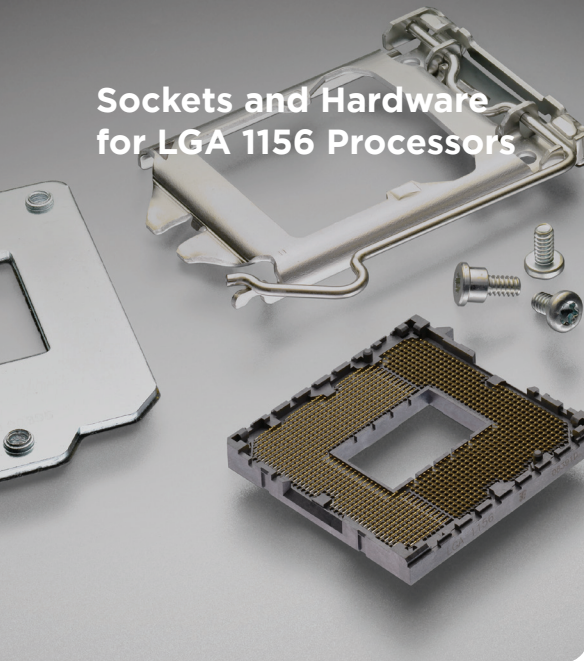


Introducing Sockets and Hardware for LGA 1156 Processors

TE Connectivity's surface mount LGA socket was designed for use with Intel's® Core™ i7 LGA 1156 processor. The contacts have solder balls for surface mount onto the PCB, while the top side provides a cantilever beam interface to the package. The integrated lever mechanism (ILM) generates the Z-axis compression load. A robust bolster plate eliminates PCB bowing during compression. The sockets have been validated to Intel Design Guides.



Sockets and Hardware for LGA 1156 Processors



KEY FEATURES

- 1156 contacts with a 0.914mm x 0.914mm grid.
- Available with 15 Gold or Gold flash contact plating.
- Socket housing facilitates efficient soldering to the PCB board.
- Socket is supplied with a cap to facilitate vacuum pick and place.
- Backplates are available in zinc or nickel plating.
- ILM, screws and backplate must be ordered separately. Kits are also available for ease in ordering.
- Each ILM assembly requires two ILM screws and one ILM shoulder screw.

Tyco Electronics Corporation Technical Support Center

Internet: www.tycoelectronics.com/help

USA: +1 (800) 522-6752

Canada: +1 (905) 470-4425

Central America
& Mexico

+52 (0) 55-1106-0814

South America: +55 (0) 11-2103-6000

Germany: +49 (0) 6251-133-1999

UK: +44 (0) 8706-080208

France: +33 (0) 1-3420-8686

Netherlands: +31 (0) 73-6246-999

China: +86 (0) 400-820-6015

www.tycoelectronics.com

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APPLICATIONS

- Desktop computers
- Low end servers

ELECTRICAL

- Low level bulk contact resistance: 22 milliohms max avg.
- Insulation resistance: 800 milliohms min. @ 500 VDC

MECHANICAL

- Nominal Deflection: .45 mm
- Durability: 30 cycles
- Package mating and unmating operation force of lever: 49N (5kgf) maximum

MATERIALS

- Socket assembly
Contact: Copper Alloy, gold plating at contact area on nickel under plating.
Base housing: High temperature thermoplastic UL94V-0
Cap: High temperature thermoplastic UL94V-0
- ILM load plate and lever: Stainless steel
- ILM frame, ILM screw and shoulder screw: Steel
- ILM Insulator: Polypropylene
- Backplate assembly: Steel, zinc or nickel plated
- Backplate Insulator: Polypropylene

APPLICATIONS AND SPECIFICATION

- Application specification 114-5444
- Instruction sheet 411-78321
- Product Spec 108-78586

PRODUCT OFFERINGS

Part Number	Description	Plating
2040540-1	LGA 1156 Socket	15 Gold
2040540-2	LGA 1156 Socket	Gold Flash
2013882-1	ILM Assembly	
2013882-2	ILM Assembly with ILM screws	
2013883-1	Back plate assembly	Zinc
2013883-2	Back plate assembly	Nickel
2013884-1	Shoulder Screw	
2040979-1	ILM Screw	

ILM/Back Plate Kits

Part No.	2013882-1 ILM Assembly	2013884-1 Shoulder Screw	2040979-1 ILM Screw	2013883-1 Back Plate Assembly - Zinc Plated	2013883-2 Back Plate Assembly - Ni Plated	Qty per kit
2069838-1	1	1	2	1	0	
2069838-3	0	1	2	1	0	
2069838-4	1	1	2	0	1	
2069838-5	0	1	2	0	1	



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